

AMENDMENT TO THE ABSTRACT

The following abstract will replace all prior versions of the abstract in the application:

~~The present invention provides a connector chip capable of preventing electrical shorting between adjoining electrodes and also capable of readily connecting a plurality of electrodes on a first circuit substrate and a plurality of electrodes on a second circuit substrate without using a dedicated mounting device or the like. A plurality of conductive paths 5 are formed on an outer periphery surface constituted by continuous four surfaces 9A to 9D of an insulating substrate 3 including six surfaces of the surfaces 9A to 9D and surfaces 9E and 9F. Each of the conductive paths 5 goes round on the outer periphery surface. The conductive paths 5 are formed on the outer periphery surface at a predetermined interval in an opposing direction in which the remaining two surfaces 9E and 9F are opposing to each other. Each of insulating layers 7 having a property of repelling molten solder is formed between portions of each two adjoining conductive paths located on a pair of the surfaces 9A and 9B. The width of a conductive path formed portion 3A with a conductive path 5 formed thereon, orthogonal to a center line C is formed to be smaller than the width of a conductive path unformed portion 3B with no conductive path 5 formed thereon, orthogonal to the center line C.~~

A connector chip is provided that includes a rectangular insulating substrate and multiple conductive paths formed on an outer peripheral surface of the substrate at predetermined intervals. Insulating layers formed between adjacent conductors have a property of repelling molten solder. Thus, the connector chip prevents electrical short circuiting between the conductors.